

Title (en)

ADAPTER ELEMENT FOR CONNECTING AN ELECTRONICS COMPONENT TO A HEAT SINK ELEMENT, SYSTEM COMPRISING AN ADAPTER ELEMENT OF THIS KIND, AND METHOD FOR PRODUCING AN ADAPTER ELEMENT OF THIS KIND

Title (de)

ADAPTERELEMENT ZUM ANBINDEN EINES ELEKTRONIKBAUTEILS AN EIN KÜHLKÖRPERELEMENT, SYSTEM MIT EINEM SOLCHEN ADAPTERELEMENT UND VERFAHREN ZUM HERSTELLEN EINES SOLCHEN ADAPTERELEMENTS

Title (fr)

ÉLÉMENT ADAPTATEUR POUR RELIER UN COMPOSANT ÉLECTRONIQUE À UN ÉLÉMENT DE CORPS DE REFROIDISSEMENT, SYSTÈME MUNI D'UN TEL ÉLÉMENT ADAPTATEUR ET PROCÉDÉ DE FABRICATION D'UN TEL ÉLÉMENT ADAPTATEUR

Publication

EP 3973602 A1 20220330 (DE)

Application

EP 20725456 A 20200506

Priority

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- EP 2020062503 W 20200506

Abstract (en)

[origin: WO2020233987A1] Adapter element (10) for connecting an electronics component (30), which has a first connection region (31), a second connection region (32) and at least one active element region (5) which is arranged between the first connection region (31) and the second connection region (32), to a heat sink element (20), comprising: • - an insulation layer (15) which runs along a plane of main extent (HSE), and • - at least one first web element (11) and one second web element (12), • -- which are arranged next to one another in a direction that runs parallel in relation to the plane of main extent (HSE), so as to form a clearance (13), • -- which, in the mounted state, are arranged between the insulation layer (15) and the electronics component (30), in a direction that runs perpendicularly in relation to the plane of main extent (HSE) , and • -- on the end sides (18) of which, which end sides are averted from the insulation layer (15), the electronics component (30) is arranged in the mounted state, wherein a distance (A) between the first web element (11) and the second web element (12), which distance is measured parallel in relation to the plane of main extent, is less than 350 µm.

IPC 8 full level

H01S 5/024 (2006.01); **C04B 41/90** (2006.01); **H01L 23/12** (2006.01); **H01L 23/373** (2006.01); **H01L 23/473** (2006.01); **H01S 5/022** (2021.01); **H01S 5/40** (2006.01)

CPC (source: EP US)

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